

REMARKS/ARGUMENTS

In the most recent Office Action, claims 1-7 were examined. Claims 1-7 are rejected. Accordingly, claims 1-7 are pending in the present application. No new matter is added.

SPECIFICATION

The Office Action states that the title of the invention is not descriptive. Applicants submit with this response a new title for the invention that conveys the content of the inventive subject matter to comply with the requirement for descriptiveness. Applicants respectfully submit that the objection to the title is now overcome, and respectfully requests that it be reconsidered and withdrawn.

CLAIM REJECTIONS - 35 U.S.C. §102

The Office Action states that claims 1-7 are rejected under 35 U.S.C. §102(b) as being anticipated by either Arakawa et al. (U.S. Patent No. 5,313,150) or Maekawa et al. (U.S. Patent No. 6,137,705). In particular, the Office Action states that the two references contain each and every element recited in claims 1-7. The rejections are respectfully traversed.

Applicants note that both the disclosures by Arakawa et al. and Maekawa et al. deal with three phase motor drive systems. That is, in each instance a power inverter is disclosed with three sets of half-bridge circuits, each of which is used to drive a phase of the motor drive circuit. In contrast, the present invention recites an H-bridge driver for driving electrical load. That is, the H-bridge consists exclusively of two half bridge drivers for operating the load, which requires a significant departure from the operation described in the disclosures by Arakawa et al. and Maekawa et al. Accordingly, claims 1-7 recite elements not disclosed in the cited references.

In addition, claim 1 of the present invention recites:

a conductive support plate for supporting said first and second high side MOSFETs and said IC; and

a common insulation housing enclosing said first and second high side MOSFETs and said IC; and connection pins extending from said housing.

The disclosures by Arakawa et al. and Maekawa et al. are completely devoid of a conductive support plate for supporting a first and second high side MOSFET and the control IC with a common insulation housing enclosing the first and second high side MOSFETs and IC. Instead, Arakawa et al. appears to recite a dielectric separation substrate for an integrated circuit that actually insulates various drive components from each other. The disclosure by Maekawa et al. similarly fails to show a conductive support plate for supporting the first and second high side MOSFETs and the IC and a common insulation housing enclosing the first and second high side MOSFETs and the IC. Instead, Maekawa et al. appear to show a separately mounted micro computer isolated from the inverter through various high voltage ICs and protection circuits.

Accordingly, claim 1 recites a number of elements that are not disclosed in either of the references by Arakawa et al. or Maekawa et al. Because claim 1 recites elements not found in either of the references, Applicants respectfully submit that the rejection of claim 1 under 35 U.S.C. §102(b) is overcome, and respectfully requests that it be reconsidered and withdrawn.

Claims 2-7 depend upon and further limit claim 1, while including all of the subject matter of claim 1. Accordingly, claims 2-7 should be allowable for all the same reasons as claim 1, and additionally because of the further combination of elements recited in each of the dependent claims. Applicants therefore respectfully request that the rejection of claims 2-7 under 35 U.S.C. §102(b) be reconsidered and withdrawn.

CONCLUSION

Applicant believes that the present response address all outstanding issues raised in the most recent Office Action. It is further respectfully believed, in view of the above amendments and discussion, that the application is now in condition for allowance, and Applicant earnestly solicits notice to that affect. If it is believed that an interview would contribute towards progress towards

allowance for the claims, the Examiner is requested to contact the undersigned counsel at the number provided below.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on July 15, 2003

Brendan J. Kennedy

Name of applicant, assignee or
Registered Representative

Brendan J. Kennedy

Signature

July 15, 2003

Date of Signature

Respectfully submitted,

Brendan J. Kennedy

Brendan J. Kennedy

Registration No.: 41,890

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

BJK:gl:lo